



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Yixing Lin et al.

SERIAL NO.: 10/071,869

FILED: February 8, 2002

FOR: HALOGEN-RESISTANT, ANODIZED ALUMINUM
FOR USE IN SEMICONDUCTOR PROCESSING
APPARATUS

§ GROUP ART UNIT: 1742

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§ EXAMINER: Janelle A. Combs

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§ Attorney Docket No.: AM-6846

§

April 28, 2005

AMENDMENT "E" UNDER 37 CFR § 1.111

**Hon. Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450**

Sir:

This Amendment "E" is in response to the Office Action mailed December 28, 2004, having a shortened statutory response period of March 28, 2005. This Amendment "E" is accompanied by a One Month Petition for Extension of Time, to extend the time for response through April 28, 2005.

Claims 8 - 12, 14, 20, 24, 25, and 28 - 34 are pending in the application.

CERTIFICATE OF MAILING UNDER 37 CFR § 1.10

I hereby certify that this paper and any documents said to accompany this paper are being deposited with the U.S. Postal Service on the date shown below with sufficient postage as U.S. EXPRESS MAIL NO. ED 330970792 US in an envelope addressed to: Mail Stop Amendment (With Fee), Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Date: April 28, 2005


Shirley L. Church, Reg. No. 31,858

Claims 15 and 16 are objected to due to an informality.

Claims 8 - 16 are rejected under 35 USC § 102(b) as being anticipated by, or in the alternative, under 35 U.S.C. § 103 (a) as obvious over U.S. Patent No. 5,039,388, to Miyashita et al.

Claims 17, 20, 28, 31, and 32 are rejected under 35 USC § 103(a) as being unpatentable over U.S. Patent No. 6,066,392, to Hisamoto et al., and Miyashita et al.

Claims 18 - 20 and 29 - 32 are rejected under 35 USC § 103(a) as being unpatentable over Hisamoto et al. and Miyashita et al., as applied to claims above, in view of "ASM Specialty Handbook®, "Aluminum and Aluminum Alloys", pp. 462 - 472.

Claims 24, 25, 33, and 34 are rejected under 35 USC § 103(a) as being unpatentable over Hisamoto et al. and Miyashita et al., in view of Japanese Patent Publication No. 08-311594.

Please amend the application as follows.